







Duration: Half-Day

Venue: Kulim Hi-Tech Park

Topics: Fundamental of Hand Soldering



Date: July 15, 2025 (Tuesday)

Duration: Half-Day

Venue: Melaka, Universiti Teknikal, Malaysia

Topics: Technical Overview for the Semiconductor

Industry



Date: July 17, 2025 (Thursday)

Duration: Full Day

Venue: SHRDC Auditorium

Topics: First Half

PCB Design

Technical Overview for the

Semiconductor Industry

Second Half

Surface Mount

Technology



Date: July 23-24, 2025 (Thursday)

Duration: Full Day

Venue: Setia Spice Convention Center, Penang

Topics: Technical Overview for the Semiconductor

Industry

Best Practices of PCB Design

Surface Mount Technology

Best Practices of Wire Harness

Best Practices of Electronic Assembly

Digitalization of Electronics Manufacturing

Advanced Packaging

Electrostatic Discharge (ESD)

CONFERENCE & FORUM

PENANG

November 12, 2025 (Wednesday)

Advanced Packaging of Semiconductor:
The Need to Build an

The Need to Bulla an Industrial Eco System



9:30 AM • Exhibition Open & Registration/ Networking Tea

10:00 AM Innaugral Session/ Welcome Address by Global Electronics Association/ Chief Guest Address

11:30 AM • keynote Address

1:00 PM INDUSTRY NETWORKING LUNCH

2:00 PM Panel Discussion

3:30 PM Award Program

4:30 PM • Networking & High-Tea

WIRE HARNESS COMPETITION JULY 23-25, 2025

Penang, Setia Spice convention centre, EMAX expo





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